

# Nrf52832 module Soldering Conditions

<b>Conditions</b>	<b>Sn-Pb Assembly</b>	<b>Pb-Free Assembly</b>
Solder Paste	Sn63/Pb37	Sn96.5/Ag3/Cu0.5
Preheat Temperature Min. (T <sub>min</sub> )	100°C	150°C
Preheat temperature Max. (T <sub>max</sub> )	150°C	200°C
Preheat Time (T <sub>min</sub> to T <sub>max</sub> )(t <sub>s</sub> )	60-120 secs	60-120 secs
Average Ramp-up Rate (T <sub>max</sub> to T <sub>p</sub> )	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time Maintained Above (TL)	60-90 secs	30-90 secs
Peak Temperature (T <sub>p</sub> )	220-235°C	230-250°C
Average Ramp-down Rate (T <sub>p</sub> to T <sub>max</sub> )	6°C/second max.	6°C/second max.
25°C to Peak Temperature Time	6 minutes max.	8 minutes max.

# Nrf52832 module recommended Reflow Oven Thermal Profile

